

example, chemical mechanical planarizing. Material will be removed during the planarizing process until planarization line 36 seen in Figure 2 is reached. The resulting interconnect structures have been metallized so as to be buried within dielectric material 14, and as such can be considered to be a metallization by "wire-down" technology. Subsequent and conventional processing can then follow in the fabrication processing of the semiconductor substrate assembly.

37 C.F.R. § 1.83(a) states that "[however], conventional features disclosed in the description and claims, where their detailed illustration is not essential for a proper understanding of the invention, should be illustrated in the drawing in the form of a graphical drawing symbol, or a labeled representation ***." The Applicant respectfully submits that feature 36 in the drawing adequately satisfies the requirements of 37 C.F.R. § 1.83(a) by one or more of the following:

- (i) feature 36 shows the claimed invention with respect to planarization recitations;
- (ii) feature 36 is a graphical drawing symbol or a labeled representation of the claimed invention with respect to planarization recitations.

The Applicant respectfully requests withdrawal of the objection to the drawings.

IN THE SPECIFICATION

Please amend the specification as follows:

Page 4, line 21: change "tantalum nitride" to --tantalum nitride--;

Page 11, line 16: change "four (4) to one (1) are" to -- four to one (4/1) are --;

Note Page 12, line 5: change "is less than" to --is more than--.

IN THE CLAIMS

Amend Claims 1-3, 5-7, 10-13, 15, 16, 20, 22-24, 27, and 28 as follows: